

Application No. 09/09746,774

**IN THE CLAIMS:**

Please substitute amended Claims 1, 2, 4, 5, 7-9, 11, 19, and 20 for pending Claims 1, 2, 4, 5, 7-9, 11, 19, and 20 as follows:

1) (Twice Amended) An improved process for manufacture and assembly of a plurality of adjoined printed wiring boards, comprising:

- (a) forming at least a first circuit pattern and a second circuit pattern on a common circuit board substrate;
- (b) fastening at least one electrically conductive pre-formed wire to connect at least the first circuit pattern to the second circuit pattern;
- (c) separating the common circuit board substrate into at least a first substrate and a second substrate with the first substrate including the first circuit pattern thereon and the second substrate including the second circuit pattern thereon; and
- (d) tilting the first substrate relative to the second substrate while maintaining the connection between the first circuit pattern and the second circuit pattern.

2) (Twice Amended) The process of claim 1, further comprising scoring the common circuit board substrate along a dividing line.

4) (Twice Amended) The process of claim 1, further comprising testing the connection between the first and second circuit patterns prior to the step of separating the common circuit board substrate into separate substrates.

5) (Amended) The process of claim 1, wherein the step of separating occurs after the step of fastening.

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7) (Amended) The process of **claim 1**, wherein:

(a) the common circuit board substrate comprises at least a first substrate section and a second substrate section;

(b) the step of forming comprises forming a plurality of circuit patterns on the first substrate section and a plurality of circuit patterns on the second substrate section; and

(c) the step of fastening further comprises making a plurality of connections between circuit patterns on the first substrate section and the second substrate section.

8) (Amended) The process of **claim 1**, wherein the step of separating further comprises pressing the common circuit board substrate along a dividing line until it separates into at least the first and second substrates.

9) (Amended) The process of **claim 1**, wherein the step of separating further comprises cutting the common circuit board substrate into a plurality of separate substrates.

Please cancel Claim 10.

11) (Amended) The process of **claim 1**, wherein the at least one electrically conductive wire comprises a pre-insulated wire.

19) (Amended) The process of **claim 1**, wherein the step of separating further comprises using an edged tool placed in contact with the common circuit board substrate along a dividing line.

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20) (Amended) The process of **claim 3**, wherein the step of fastening further comprises connecting at least one electrically conductive pre-formed wire externally from the holding fixture.

Please add the following new claims 21-25.

21) (New) The process of **claim 1**, wherein the step of fastening occurs after the step of separating.

22) (New) The process of **claim 1**, wherein the step of fastening further comprises attaching flexible ribbon wires.

23) (New) The process of **claim 1**, wherein the step of fastening further comprises using at least one electrically conductive plastic connection.

24) (New) The process of **claim 1**, wherein the step of fastening comprises an inserting process.

25) (New) The process of **claim 1**, wherein the step of fastening comprises a soldering process.

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